

## LOCTITE® DA 100 AND *LOCTITE* DA 101

### **DIE ATTACH SOLDER PASTE**

Henkel has designed a portfolio of solder die attach pastes that deliver the process flexibility, thermal performance, high reliability and ease of use that modern power device manufacturers demand. LOCTITE® DA 100 and *LOCTITE* DA 101 provide the thermal management necessary for today's smaller outline, higher functioning semiconductor power devices, while also delivering the processability and versatility associated with solder paste materials. Optimized rheology allows for printing or dispensing depending on process preferences and advanced flux technology is compatible with a wide range of reflow profiles to enable alloy adaptation when required. These products offer robust options for application-specific thermal requirements and overcome many of the issues historically associated with alternative products.

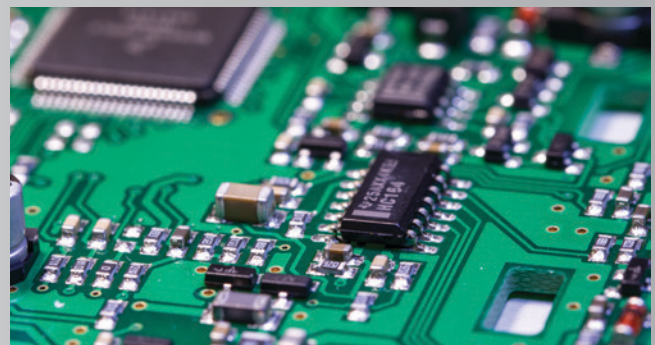
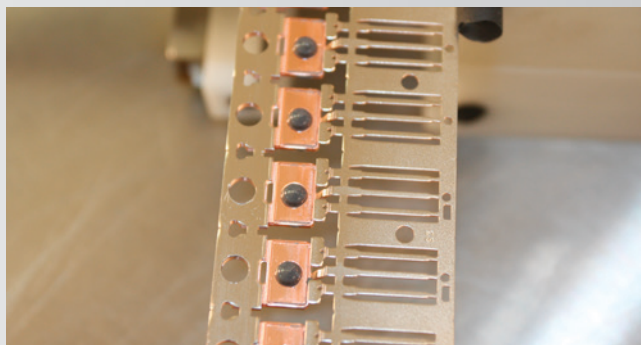
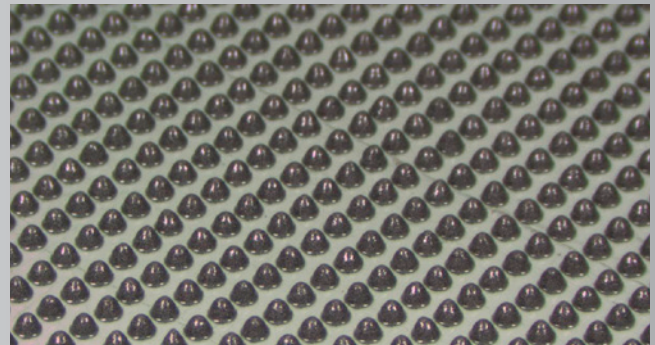


## PRODUCT PROPERTIES

| PRODUCT        | DESCRIPTION   | KEY ATTRIBUTES   | ALLOY        | PARTICLE SIZE DISTRIBUTION | VISCOSITY AT 25°C          | REFLOW ATMOSPHERE | IPC J-STD-004B CLASSIFICATION | SHELF LIFE             |
|----------------|---|--|--------------|----------------------------|----------------------------|-------------------|-------------------------------|------------------------|
| Dispensable    |   |  |              |                            |                            |                   |                               |                        |
| LOCTITE DA 100 | Halide-free, no-clean solder paste with Pb-free and high-Pb options | <ul style="list-style-type: none"> <li>• Low color residues resistant to charring in reflow</li> <li>• Very low voiding</li> <li>• Vacuum-mixed for reliable dispensing performance</li> <li>• Excellent dispense and pause time capability</li> <li>• Robust flux effective over a wide range of reflow profiles</li> </ul> | 2.5S 92A     | Type 3, 4                  | 300,000 – 310,000 at 5 rpm | Forming gas       | ROLO                          | 12 months up to -18°C  |
| Printable      |   |  |              |                            |                            |                   |                               |                        |
| LOCTITE DA 101 | Halide-free, no-clean solder paste with Pb-free and high-Pb options | <ul style="list-style-type: none"> <li>• Low color residues resistant to charring in reflow</li> <li>• Very low voiding</li> <li>• Robust flux effective over a wide range of reflow profiles</li> <li>• The rheology of LOCTITE DA 101 ensures excellent print definition and slump resistance</li> </ul>                   | 2.5S 92A 95A | Type 3                     | 600,000 at 5 rpm           | Forming gas       | ROLO                          | 6 months at 0°C – 10°C |

## ALLOYS AVAILABLE

| HENKEL CODE | ALLOY             | MELTING POINT (°C) |
|-------------|-------------------|--------------------|
| High-Lead   |                   |                    |
| 2.5S        | Pb92.5/Sn05/Ag2.5 | 287 – 296          |
| Lead-Free   |                   |                    |
| 92A         | Sn91.5/Sb8.5      | 235 – 243          |
| 95A         | Sn95/Sb5          | 236 – 240          |



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